

Single 2-Input Positive-AND Gate

Description

The FLG1G08 Single 2-input positive-AND gate is designed for 1.65V to 5.5V V_{CC} operation.

The FLG1G08 device performs the Boolean function $Y = A \bullet B$ or $Y = \overline{\overline{A} + \overline{B}}$ in positive logic. The device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The FLG1G08 is available in Green SOT23-5, SC70-5 and XDFN1X1-6 packages. It operates over an ambient temperature range of -40°C to 125°C.

Features

- Operating Voltage Range: 1.65V to 5.5V
- Low Power Consumption:1µA (Max)
- Operating Temperature Range: -40°C to +125°C
- Input accept Voltage to 5.5V
- High Output Drive: ±24mA at V_{CC}=3.0V
- Micro SIZE PACKAGES: SOT23-5, SC70-5, XDFN1X1-6

Applications

- Active Noise Elimination
- Bar Code Scanner
- Blood Pressure Monitor
- CPAP Machine

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- Fingerprint identification
- Network attached storage (NAS)



Order information (1)

Mode	Package	Specified Temperature range	Ordering Number	Packing Option
	SOT23-5	-40°C to +125°C	FLG1G08YSOT235G/TR	Tape and Reel,3000
FLG1G08	SC70-5 (2)	-40°C to +125°C	FLG1G08YSC705G/TR	Tape and Reel,3000
	XDFN1X1-6	-40°C to +125°C	FLG1G08YXDFN1X1G/TR	Tape and Reel,5000

Note:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document.
- (2) Equivalent to SOT353.

Logic Symbol



Function Table

INP	OUTPUT	
A	В	Y
Н	Н	Н
L	Н	L
Н	L	L
L	L	L

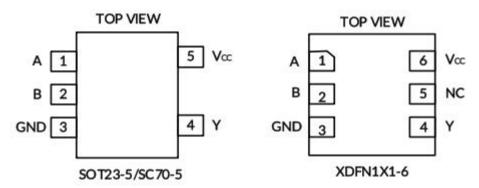
Note:

H=High Voltage Level

L=Low Voltage Level

$$Y = A \bullet B$$

Pin Configuration





Pin Description

Pin		N	I/O T (1)	E
SOT23-5/SC70-5	XDFN1X1-6	Name I/O Type (1) Function	runction	
1	1	A	I	Input
2	2	В	I	Input
3	3	GND	-	Ground Pin
4	4	Y	0	Y Output
-	5	NC	-	Not connected
5	6	V_{CC}	-	Power Pin

Note:

I=input, O=output.

Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)(2)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range (2)		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impedan	ice or power-off state ⁽²⁾	-0.5	6.5	V
Vo	Voltage range applied to any output in the high or low st	ate (2)(3)	-0.5	V _{CC} +0.5	V
I _{IK}	Input clamp current	$V_I < 0$		-50	mA
Iok	Output clamp current	V ₀ <0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through V _{CC} or GND			±100	mA
		SOT23-5		208	
θ_{JA}	Package thermal impedance (4)	SC70-5		283	°C/W
	XDFN1X1-6			438	C/ W
TJ	T _J Junction temperature ⁽⁵⁾			150	°C
T_{stg}	T _{stg} Storage temperature			150	°C

- (1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the Recommended Operating Conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD-51.
- (5) The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A . The maximum allowable power dissipation at



any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.

ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

		Value	Unit
	Human-body model (HBM)), per EIA/JESD22-a114, all pins	± 4000	V
V E144-4:- 4:1	Charged device model (CDM), per JS-002, all pins	±1000	V
V _(ESD) Electrostatic discharge	Machine model (MM)), per EIA/JESD22-a115, all pins	±200	V



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Recommanded Operating Range

over recommended operating free-air temperature range (TYP values are at T_A = +25°C, unless otherwise noted.) (1)

Parameter	Symbol	Test Conditions	Min	Max	Unit
C 1 L	1 7	Operating	1.65	5.5	
Supply voltage	V_{CC}	Data retention only	1.5	5.5	V
		V _{CC} =1.65V to 1.95V	0.65×V _{CC}		
	T 7	V _{CC} =2.3V to 2.7V	1.7		
High-level input voltage	$ m V_{IH}$	V _{CC} =3V to 3.6V	2.2		V
		V _{CC} =4.5V to 5.5V	$0.7 \times V_{CC}$		
		V _{CC} =1.65V to 1.95V		$0.3 \times V_{CC}$	
	$ m V_{IL}$	V _{CC} =2.3V to 2.7V		0.7	
Low-level input voltage		$V_{CC}=3V$ to 3.6V		0.8	V
		V _{CC} =4.5V to 5.5V		0.3 xV_{CC}	
Input voltage	$V_{\rm I}$		0	5.5	V
Output voltage	Vo		0	V_{CC}	V
		V_{CC} =1.8V± 0.15V,2.5V ± 0.2V		20	
Immut transition rise £-11	4 4.	V _{CC} =3.3V± 0.3V		10	ns/V
Input transition rise or fall	t_r, t_f	V _{CC} =5V± 0.5V		5	
Operating temperature	T_A		-40	+125	°C

Note: (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



Electrical Characteristics

DC Characteristics

over recommended operating free-air temperature range (TYP values are at T_A = +25°C, unless otherwise noted.) (1)

]	Parameter	Test Conditions	V _{CC}	Temp	Min ⁽²⁾	Typ ⁽³⁾	Max ⁽²⁾	Unit
		$I_{OH} = -100 \mu A$	1.65V to 5.5V		V _{CC} -0.1			
		$I_{OH} = -4mA$	1.65V		1.2			
	17	$I_{OH} = -8mA$	2.3V		1.9			
	V_{OH}	$I_{OH} = -16mA$	27/		2.4			
		$I_{OH} = -24mA$	3V	Full	2.3			V
		$I_{OH} = -32mA$	4.5V		3.8			
		$I_{OL}=100\mu A$	1.65V to 5.5V				0.1	
		$I_{OL} = 4mA$	1.65V				0.45	
	1 7	$I_{OL} = 8mA$	2.3V				0.3	
	V_{OL}	$I_{OL} = 16mA$	277				0.4	
		$I_{OL} = 24mA$	3V	Full			0.55	V
		$I_{OL} = 32mA$	4.5V				0.55	
т.	A D: (W CAN CAN	011. 7.71	+25°C		±0.1	±1	
$I_{\rm I}$	A or B inputs	V _I =5.5V or GND	0V to 5.5V	Full			±5	μΑ
	Ť	V V C C V	0	+25°C		±0.1	±1	
	$ m I_{off}$	$V_{\rm I}$ or $V_{\rm O}$ =5.5V	0	Full			±10	μA
	T	W CM CMD I O	1 (5)	+25°C		0.1	1	
	I_{CC}	V_I =5.5V or GND, I_O =0	1.65V to 5.5V	Full			10	μA
		One input at V _{CC} -0.6V,						
	ΔI_{CC}	Other inputs at V _{CC} or GND	3V to 5.5V	Full			500	μΑ

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.
- (2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.



AC Characteristics

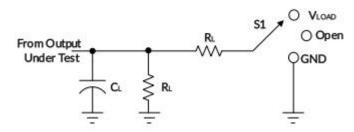
over recommended operating free-air temperature range (TYP values are at $T_A = +25$ °C, unless otherwise noted.) (1)

Parameter	Symbol	Test Cor	Min ⁽²⁾	Typ ⁽³⁾	Max ⁽²⁾	Unit	
		V _{CC} =1.8V±0.15V	$C_L=30pF, R_L=1k\Omega$		11.6		
		V _{CC} =2.5V±0.2V	$C_L=30pF, R_L=500\Omega$		6.6		
Propagation Delay	$t_{\rm pd}$	V _{CC} =3.3V±0.3V	C_L =50pF, R_L =500 Ω		5.4		ns
		V _{CC} =5V±0.5 V	C_L =50pF, R_L =500 Ω		4.3		
Input Capacitance	C_{i}	V _{CC} =0V			4		pF
Power dissipation	C	V _{CC} =3.3V	C 10MH		26		Г
capacitance	C_{pd}	V _{CC} =5V	f=10MHz	31		pF	

Note:

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.
- (2) This parameter is ensured by design and/or characterization and is not tested in production.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

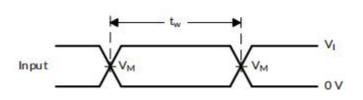
Parameter Measurement Information

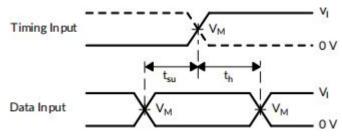


Test	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	$ m V_{LOAD}$
t _{PHZ} /t _{PZH}	GND

77	INPUTS		V	17	C	D	N/
V_{CC}	VI	tr/tf	$ V_{\mathrm{M}}$	V_{LOAD} C_L		R_L	V_{Δ}
1.8V±0.15V	V _{CC}	≤2ns	V _{CC} /2	2 x V _{CC}	30pF	1kΩ	0.15V
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	2 x V _{CC}	30pF	500Ω	0.15V
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	2 x V _{CC}	50pF	500Ω	0.3V

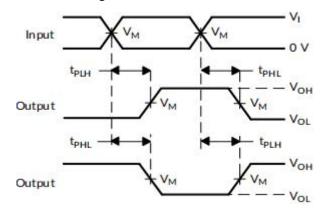


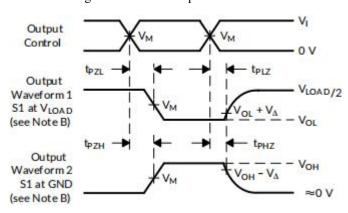




Voltage Waveforms Pulse Duration

Voltage Waveforms Setup And Hold Times





Voltage Waveforms Propagation Delay Times Invertion And Noninverting Outputs

Voltage Waveforms Enable And Disable Times Low-And High-Level Enabling

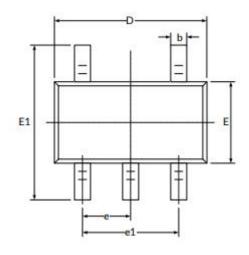
- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50\Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

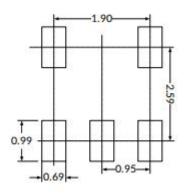
Figure 1. Load Circuit and Voltage Waveforms



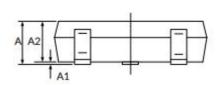
Package Outline Dimensions(All dimensions in mm.)

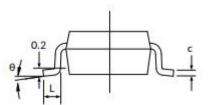
Package Type: SOT23-5 (3)





RECOMMENDED LAND PATTERN (Unit: mm)



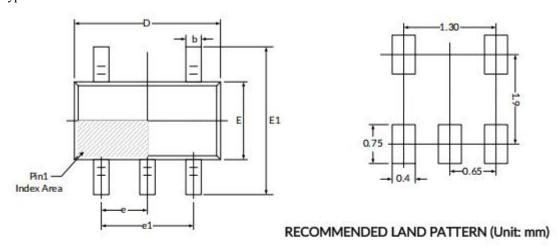


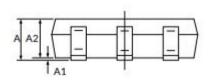
Crossle of	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A (1)	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D ⁽¹⁾	2.820	3.020	0.111	0.119	
E (1)	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
e	0.950(I	BSC) (2)	0.037(BSC) ⁽²⁾		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

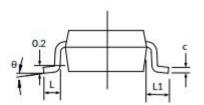
- 1. Plastic or metal protrusions of $0.15 \mathrm{mm}$ maximum per side are not included.
- 2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
- 3. This drawing is subject to change without notice.



Package Type: SC70-5 (3)





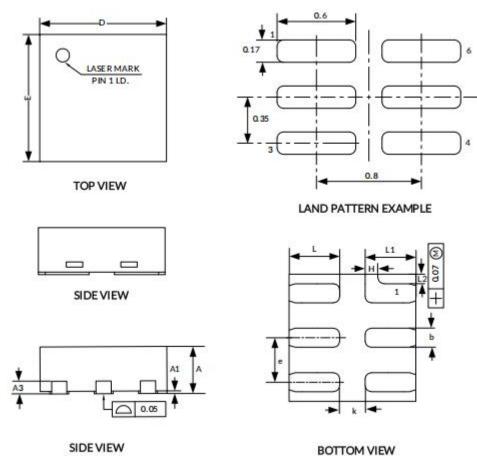


Cross had	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A (1)	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.150	0.350	0.006	0.014	
С	0.080	0.150	0.003	0.006	
D (1)	2.000	2.200	0.079	0.087	
E (1)	1.150	1.350	0.045	0.053	
E1	2.150	2.450	0.085	0.096	
e	0.650(I	BSC) (2)	0.026(1	BSC) (2)	
e1	1.300(I	1.300(BSC) (2)		BSC) (2)	
L	0.260	0.460	0.010	0.018	
L1	0.525		0.021		
θ	0°	8°	0°	8°	

- 1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
- 2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
- 3. This drawing is subject to change without notice.



Package Type: XDFN1X1-6 (3)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A (1)	0.340	0.400	0.013	0.016
A1	0.000	0.050	0.000	0.002
A3	0.100 (REF) ⁽²⁾		0.004 (REF) ⁽²⁾	
b	0.100	0.200	0.004	0.008
D (1)	0.950	1.050	0.037	0.041
E (1)	0.950	1.050	0.037	0.041
e	0.300	0.400	0.012	0.016
Н	0.100 (REF) ⁽²⁾		0.004 (REF) ⁽²⁾	
K	0.150		0.006	
L	0.350	0.450	0.014	0.018
L1	0.350	0.450	0.014	0.018
L2	0.075 (REF) ⁽²⁾		0.003 (REF)	

- 1. Plastic or metal protrusions of $0.15 \mathrm{mm}$ maximum per side are not included.
- 2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
- 3. This drawing is subject to change without notice.

FLG1G08



Important Notice And Disclaimer

- We reserves the right to change the instruction manual without prior notice.
- Any semiconductor product has a certain possibility of failure or malfunction under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design and overall manufacturing to avoid potential failure risks that may cause personal injury or property damage.
- The improvement of product quality is endless, our company will be dedicated to provide customers with better products.